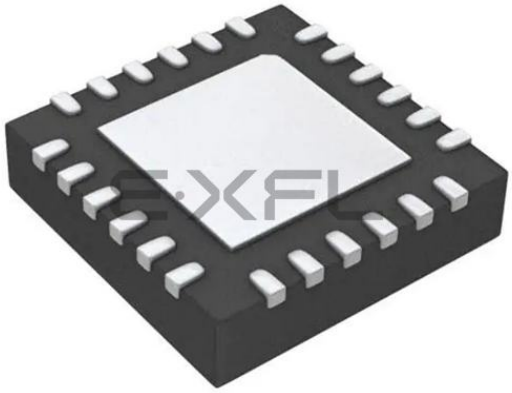

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-WFQFN Exposed Pad
Supplier Device Package	24-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f987-c-gm

2. Ordering Information

Table 2.1. Product Selection Guide

Ordering Part Number	MIPS (Peak)	Flash Memory (kB)	RAM (bytes)	SmaRTClock Real Time Clock	SMBus/I^2C, UART, Enhanced SPI	Timers (16-bit)	Programmable Counter Array	Digital Port I/Os	Analog to Digital Converter Inputs	ADC with internal voltage reference and temperature sensor	Capacitive Touch Inputs	Programmable Current Reference	Analog Comparators	Lead-free (RoHS Compliant)	Package
C8051F980-C-GM	25	8	512	✓	✓	4	✓	16	9	12-bit	—	✓	1	✓	QFN-20
C8051F981-C-GM	25	8	512	✓	✓	4	✓	16	—	—	—	✓	1	✓	QFN-20
C8051F982-C-GM	25	4	512	✓	✓	4	✓	16	9	10-bit	—	✓	1	✓	QFN-20
C8051F983-C-GM	25	4	512	✓	✓	4	✓	16	—	—	—	✓	1	✓	QFN-20
C8051F985-C-GM	25	2	512	✓	✓	4	✓	16	—	—	—	✓	1	✓	QFN-20
C8051F986-C-GM	25	8	512	✓	✓	4	✓	17	10	12-bit	—	✓	1	✓	QFN-24
C8051F986-C-GU	25	8	512	✓	✓	4	✓	17	10	12-bit	—	✓	1	✓	QSOP-24
C8051F987-C-GM	25	8	512	✓	✓	4	✓	17	—	—	—	✓	1	✓	QFN-24
C8051F987-C-GU	25	8	512	✓	✓	4	✓	17	—	—	—	✓	1	✓	QSOP-24
C8051F988-C-GM	25	4	512	✓	✓	4	✓	17	10	10-bit	—	✓	1	✓	QFN-24
C8051F988-C-GU	25	4	512	✓	✓	4	✓	17	10	10-bit	—	✓	1	✓	QSOP-24
C8051F989-C-GM	25	4	512	✓	✓	4	✓	17	—	—	—	✓	1	✓	QFN-24
C8051F989-C-GU	25	4	512	✓	✓	4	✓	17	—	—	—	✓	1	✓	QSOP-24
C8051F990-C-GM	25	8	512	✓	✓	4	✓	16	9	12-bit	13	✓	1	✓	QFN-20
C8051F991-C-GM	25	8	512	✓	✓	4	✓	16	—	—	13	✓	1	✓	QFN-20
C8051F996-C-GM	25	8	512	✓	✓	4	✓	17	10	12-bit	14	✓	1	✓	QFN-24
C8051F996-C-GU	25	8	512	✓	✓	4	✓	17	10	12-bit	14	✓	1	✓	QSOP-24
C8051F997-C-GM	25	8	512	✓	✓	4	✓	17	—	—	14	✓	1	✓	QFN-24
C8051F997-C-GU	25	8	512	✓	✓	4	✓	17	—	—	14	✓	1	✓	QSOP-24

Note: Starting with silicon revision C, the ordering part numbers have been updated to include the silicon revision and use this format: "C8051F990-C-GM". Package marking diagrams are included as Figure 3.4, Figure 3.5, and Figure 3.6 to identify the silicon revision.

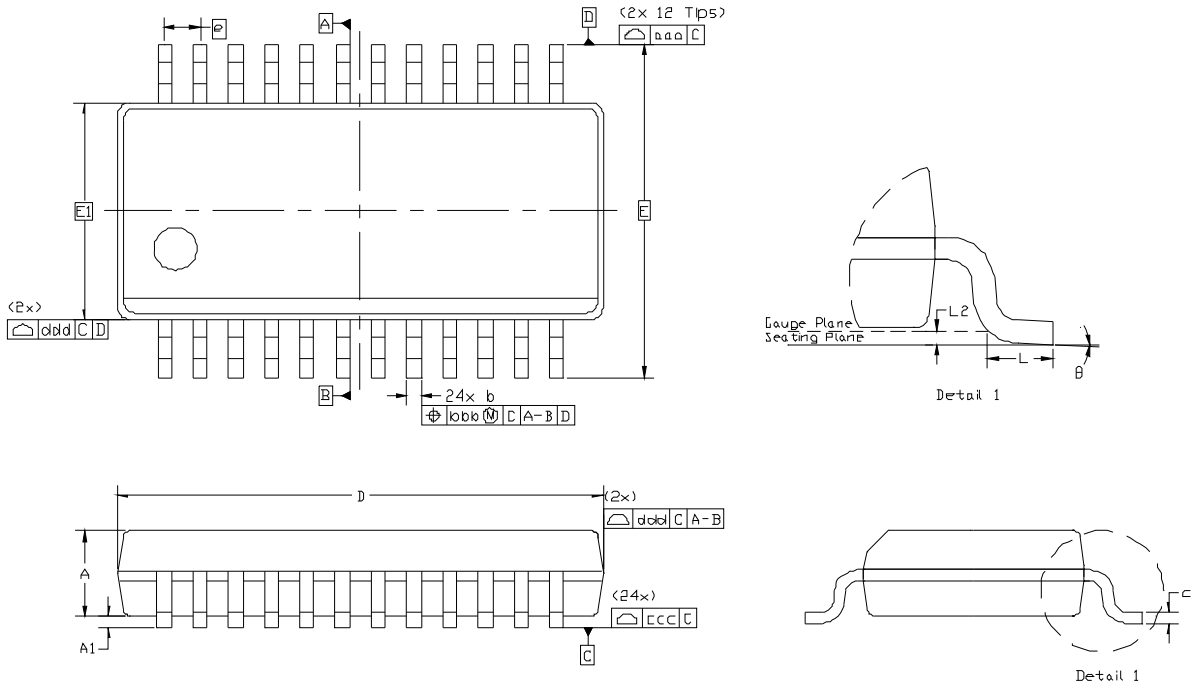

Figure 3.11. QSOP-24 Package Diagram

Table 3.6. QSOP-24 Package Dimensions

Dimension	Min	Typ	Max	Dimension	Min	Typ	Max
A	—	—	1.75	L	0.40	—	1.27
A1	0.10	—	0.25	L2	0.25 BSC		
b	0.20	—	0.30	θ	0º	—	8º
c	0.10	—	0.25	aaa	0.20		
D	8.65 BSC.			bbb	0.18		
E	6.00 BSC			ccc	0.10		
E1	3.90 BSC			ddd	0.10		
e	0.635 BSC						

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to JEDEC outline MO-147, variation AE.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 4.10. ADC0 Electrical Characteristics (Continued)

V_{DD} = 1.8 to 3.6 V, VREF = 1.65 V (REFSL[1:0] = 11), –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Analog Inputs					
ADC Input Voltage Range	Single Ended (AIN+ – GND)	0	—	VREF	V
Absolute Pin Voltage with respect to GND	Single Ended	0	—	VDD	V
Sampling Capacitance	1x Gain 0.5x Gain	—	16 13	—	pF
Input Multiplexer Impedance		—	5	—	kΩ
Power Specifications					
Power Supply Current (V_{DD} supplied to ADC0)	Normal Power Mode: Conversion Mode (300 ksps) Tracking Mode (0 ksps) Low Power Mode: Conversion Mode (150 ksps) Tracking Mode (0 ksps)	 — — — —	 650 740 370 400	 — — — —	µA
Power Supply Rejection	Internal High Speed VREF External VREF	— —	67 74	— —	dB

1. INL and DNL specifications for 12-bit mode do not include the first or last four ADC codes.
2. The maximum code in 12-bit mode is 0xFFFC. The Full Scale Error is referenced from the maximum code.
3. Performance in 8-bit mode is similar to 10-bit mode.

Table 4.11. Temperature Sensor Electrical Characteristics

V_{DD} = 1.8 to 3.6 V, –40 to +85 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Linearity		—	±1	—	°C
Slope		—	3.40	—	mV/°C
Slope Error*		—	40	—	µV/°C
Offset	Temp = 25 °C	—	1025	—	mV
Offset Error*	Temp = 25 °C	—	18	—	mV
Temperature Sensor Turn-On Time		—	1.7	—	µs
Supply Current		—	35	—	µA

***Note:** Represents one standard deviation from the mean.

Table 4.14. Comparator Electrical Characteristics

V_{DD} = 1.8 to 3.6 V, –40 to +85 °C unless otherwise noted.

Parameter	Conditions	Min	Typ	Max	Units
Response Time: Mode 0, V_{DD} = 2.4 V, V_{CM}^* = 1.2 V	CP0+ – CP0– = 100 mV	—	120	—	ns
	CP0+ – CP0– = –100 mV	—	110	—	ns
Response Time: Mode 1, V_{DD} = 2.4 V, V_{CM}^* = 1.2 V	CP0+ – CP0– = 100 mV	—	180	—	ns
	CP0+ – CP0– = –100 mV	—	220	—	ns
Response Time: Mode 2, V_{DD} = 2.4 V, V_{CM}^* = 1.2 V	CP0+ – CP0– = 100 mV	—	350	—	ns
	CP0+ – CP0– = –100 mV	—	600	—	ns
Response Time: Mode 3, V_{DD} = 2.4 V, V_{CM}^* = 1.2 V	CP0+ – CP0– = 100 mV	—	1240	—	ns
	CP0+ – CP0– = –100 mV	—	3200	—	ns
Common-Mode Rejection Ratio		—	1.5	—	mV/V
Inverting or Non-Inverting Input Voltage Range		–0.25	—	V_{DD} + 0.25	V
Input Capacitance		—	12	—	pF
Input Bias Current		—	1	—	nA
Input Offset Voltage		–7	—	+7	mV
Power Supply					
Power Supply Rejection		—	0.1	—	mV/V
Power-up Time	VDD = 3.6 V	—	0.6	—	µs
	VDD = 3.0 V	—	1.0	—	µs
	VDD = 2.4 V	—	1.8	—	µs
	VDD = 1.8 V	—	10	—	µs
Supply Current at DC	Mode 0	—	23	—	µA
	Mode 1	—	8.8	—	µA
	Mode 2	—	2.6	—	µA
	Mode 3	—	0.4	—	µA

***Note:** Vcm is the common-mode voltage on CP0+ and CP0–.

5.6. Programmable Window Detector

The ADC Programmable Window Detector continuously compares the ADC0 output registers to user-programmed limits, and notifies the system when a desired condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (AD0WINT in register ADC0CN) can also be used in polled mode. The ADC0 Greater-Than (ADC0GTH, ADC0GTL) and Less-Than (ADC0LTH, ADC0LTL) registers hold the comparison values. The window detector flag can be programmed to indicate when measured data is inside or outside of the user-programmed limits, depending on the contents of the ADC0 Less-Than and ADC0 Greater-Than registers.

SFR Definition 5.8. ADC0GTH: ADC0 Greater-Than High Byte

Bit	7	6	5	4	3	2	1	0
Name	AD0GT[15:8]							
Type	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Page = 0x0; SFR Address = 0xC4

Bit	Name	Function
7:0	AD0GT[15:8]	**ADC0 Greater-Than High Byte.** Most Significant Byte of the 16-bit Greater-Than window compare register.

SFR Definition 5.9. ADC0GTL: ADC0 Greater-Than Low Byte

Bit	7	6	5	4	3	2	1	0
Name	AD0GT[7:0]							
Type	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Page = 0x0; SFR Address = 0xC3

Bit	Name	Function
7:0	AD0GT[7:0]	**ADC0 Greater-Than Low Byte.** Least Significant Byte of the 16-bit Greater-Than window compare register.
Note: In 8-bit mode, this register should be set to 0x00.		

5.9. Voltage and Ground Reference Options

The voltage reference MUX is configurable to use an externally connected voltage reference, the internal voltage reference, or one of two power supply voltages (see Figure 5.10). The ground reference MUX allows the ground reference for ADC0 to be selected between the ground pin (GND) or a port pin dedicated to analog ground (P0.1/AGND).

The voltage and ground reference options are configured using the REF0CN SFR described on page 90. Electrical specifications are can be found in the Electrical Specifications Chapter.

Important Note About the V_{REF} and AGND Inputs: Port pins are used as the external V_{REF} and AGND inputs. When using an external voltage reference or the internal precision reference, P0.0/VREF should be configured as an analog input and skipped by the Digital Crossbar. When using AGND as the ground reference to ADC0, P0.1/AGND should be configured as an analog input and skipped by the Digital Crossbar. Refer to Section “21. Port Input/Output” on page 215 for complete Port I/O configuration details. The external reference voltage must be within the range $0 \le V_{REF} \le VDD$ and the external ground reference must be at the same DC voltage potential as GND.

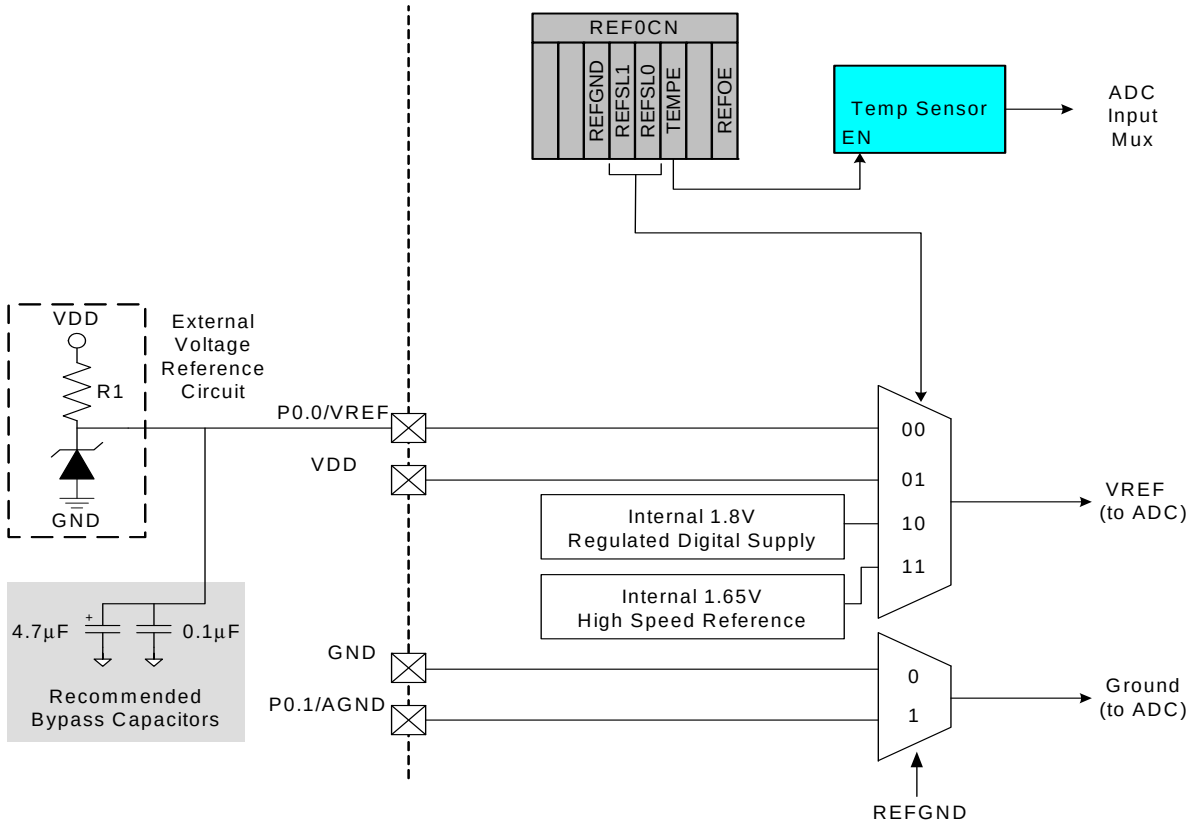

Figure 5.10. Voltage Reference Functional Block Diagram

8. Capacitive Sense (CS0)

The Capacitive Sense subsystem uses a capacitance-to-digital circuit to determine the capacitance on a port pin. The module can take measurements from different port pins using the module's analog multiplexer. The module is enabled only when the CS0EN bit (CS0CN) is set to 1. Otherwise the module is in a low-power shutdown state. The module can be configured to take measurements on one port pin or a group of port pins, using auto-scan. A selectable gain circuit allows the designer to adjust the maximum allowable capacitance. An accumulator is also included, which can be configured to average multiple conversions on an input channel. Interrupts can be generated when CS0 completes a conversion or when the measured value crosses a threshold defined in CS0THH:L.

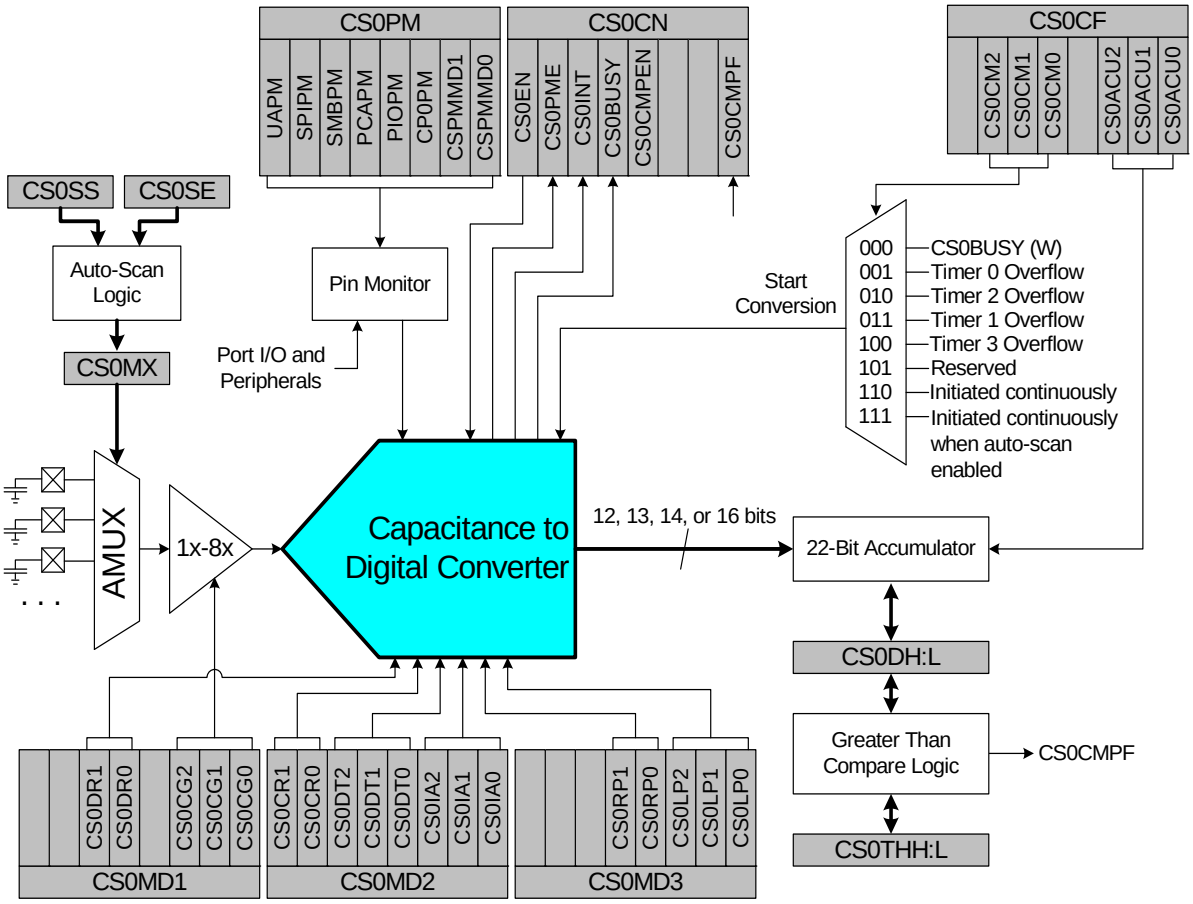

Figure 8.1. CS0 Block Diagram

SFR Definition 12.1. SFR Page: SFR Page

Bit	7	6	5	4	3	2	1	0
Name	SFRPAGE[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = All; SFR Address = 0xA7

Bit	Name	Function
7:0	SFRPAGE[7:0]	**SFR Page.** Specifies the SFR Page used when reading, writing, or modifying special function registers.

Table 12.3. Special Function Registers

SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

Register	Address	SFR Page	Description	Page
ACC	0xE0	All	Accumulator	126
ADC0AC	0xBA	0x0	ADC0 Accumulator Configuration	76
ADC0CF	0x97	0x0	ADC0 Configuration	75
ADC0CN	0xE8	0x0	ADC0 Control	74
ADC0GTH	0xC4	0x0	ADC0 Greater-Than Compare High	80
ADC0GTL	0xC3	0x0	ADC0 Greater-Than Compare Low	80
ADC0H	0xBE	0x0	ADC0 High	79
ADC0L	0xBD	0x0	ADC0 Low	79
ADC0LTH	0xC6	0x0	ADC0 Less-Than Compare Word High	81
ADC0LTL	0xC5	0x0	ADC0 Less-Than Compare Word Low	81
ADC0MX	0x96	0x0	AMUX0 Channel Select	84
ADC0PWR	0xBB	All	ADC0 Burst Mode Power-Up Time	77
ADC0TK	0xBC	All	ADC0 Tracking Control	78
B	0xF0	All	B Register	126
CKCON	0x8E	0x0	Clock Control	279
CLKSEL	0xA9	All	Clock Select	193
CPT0CN	0x9B	0x0	Comparator0 Control	96
CPT0MD	0x9D	0x0	Comparator0 Mode Selection	97
CPT0MX	0x9F	0x0	Comparator0 Mux Selection	99
CRC0AUTO	0x9E	All	CRC0 Automatic Control	177
CRC0CN	0x84	All	CRC0 Control	175
CRC0CNT	0x9A	All	CRC0 Automatic Flash Sector Count	178
CRC0DAT	0x86	All	CRC0 Data	176
CRC0FLIP	0x9C	All	CRC0 Flip	179
CRC0IN	0x85	All	CRC0 Input	176
CS0CF	0xAA	0x0	CS0 Configuration	108
CS0CN	0xB0	0x0	CS0 Control	107

SFR Definition 14.3. PSCTL: Program Store R/W Control

Bit	7	6	5	4	3	2	1	0
Name							PSEE	PSWE
Type	R	R	R	R	R	R	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Page =All; SFR Address = 0x8F

Bit	Name	Function
7:2	Unused	Read = 000000b, Write = don't care.
1	PSEE	**Program Store Erase Enable.** Setting this bit (in combination with PSWE) allows an entire page of Flash program memory to be erased. If this bit is logic 1 and Flash writes are enabled (PSWE is logic 1), a write to Flash memory using the MOVX instruction will erase the entire page that contains the location addressed by the MOVX instruction. The value of the data byte written does not matter. 0: Flash program memory erasure disabled. 1: Flash program memory erasure enabled.
0	PSWE	**Program Store Write Enable.** Setting this bit allows writing a byte of data to the Flash program memory using the MOVX write instruction. The Flash location should be erased before writing data. 0: Writes to Flash program memory disabled. 1: Writes to Flash program memory enabled; the MOVX write instruction targets Flash memory.

SFR Definition 15.2. PMU0FL: Power Management Unit Flag[1,2]

Bit	7	6	5	4	3	2	1	0
Name								CS0WK
Type	R	R	R	R	R	R	R	R/W
Reset	0	0	0	0	0	0	0	Varies

SFR Page = 0x0; SFR Address = 0xCE

Bit	Name	Description	Write	Read
7:1	Unused	**Unused**	Don't Care.	0000000b
0	CS0WK	**CS0 Wake-up Source Enable and Flag**	0: Disable wake-up on CS0 event. 1: Enable wake-up on CS0 event.	Set to 1 if CS0 event caused the last wake-up.

Notes:

1. The Low Power Internal Oscillator cannot be disabled and the MCU cannot be placed in Suspend or Sleep Mode if any wake-up flags are set to 1. Software should clear all wake-up sources after each reset and after each wake-up from Suspend or Sleep Modes.
2. PMU0 requires two system clocks to update the wake-up source flags after waking from Suspend mode. The wake-up source flags will read '0' during the first two system clocks following the wake from Suspend mode.

16.2. Preparing for a CRC Calculation

To prepare CRC0 for a CRC calculation, software should set the initial value of the result. The polynomial used for the CRC computation is 0x1021. The CRC0 result may be initialized to one of two values: 0x0000 or 0xFFFF. The following steps can be used to initialize CRC0.

1. Select the initial result value (Set CRC0VAL to 0 for 0x0000 or 1 for 0xFFFF).
2. Set the result to its initial value (Write 1 to CRC0INIT).

16.3. Performing a CRC Calculation

Once CRC0 is initialized, the input data stream is sequentially written to CRC0IN, one byte at a time. The CRC0 result is automatically updated after each byte is written. The CRC engine may also be configured to automatically perform a CRC on one or more 256 byte blocks. The following steps can be used to automatically perform a CRC on Flash memory.

1. Prepare CRC0 for a CRC calculation as shown above.
2. Write the index of the starting page to CRC0AUTO.
3. Set the AUTOEN bit in CRC0AUTO.
4. Write the number of 256 byte blocks to perform in the CRC calculation to CRC0CNT.
5. Write any value to CRC0CN (or OR its contents with 0x00) to initiate the CRC calculation. The CPU will not execute any additional code until the CRC operation completes. **See the note in SFR Definition 16.1. CRC0CN: CRC0 Control for more information on how to properly initiate a CRC calculation.**
6. Clear the AUTOEN bit in CRC0AUTO.
7. Read the CRC result using the procedure below.

16.4. Accessing the CRC0 Result

The internal CRC0 result is 16 bits. The CRC0PNT bits select the byte that is targeted by read and write operations on CRC0DAT and increment after each read or write. The calculation result will remain in the internal CR0 result register until it is set, overwritten, or additional data is written to CRC0IN.

19.1. Programmable Precision Internal Oscillator

All C8051F99x-C8051F98x devices include a programmable precision internal oscillator that may be selected as the system clock. OSCICL is factory calibrated to obtain a 24.5 MHz frequency. See Section “4. Electrical Characteristics” on page 48 for complete oscillator specifications.

The precision oscillator supports a spread spectrum mode which modulates the output frequency in order to reduce the EMI generated by the system. When enabled (SSE = 1), the oscillator output frequency is modulated by a stepped triangle wave whose frequency is equal to the oscillator frequency divided by 384 (63.8 kHz using the factory calibration). The deviation from the nominal oscillator frequency is +0%, –1.6%, and the step size is typically 0.26% of the nominal frequency. When using this mode, the typical average oscillator frequency is lowered from 24.5 MHz to 24.3 MHz.

Important Note: The precision internal oscillator may potentially lock up after exiting Sleep mode. Systems using Sleep Mode should switch to the low power oscillator prior to entering Sleep Mode:

1. Switch the system clock to the low power oscillator (CLKSEL = 0x04).
2. Turn off the Precision Oscillator (OSCICN &= ~0x80).
3. Enter Sleep.
4. Exit Sleep.
5. Turn on the Precision Oscillator (OSCICN |= 0x80).
6. Switch the system clock to the Precision Oscillator (CLKSEL = 0x00).

19.2. Low Power Internal Oscillator

All C8051F99x-C8051F98x devices include a low power internal oscillator that defaults as the system clock after a system reset. The low power internal oscillator frequency is 20 MHz ± 10% and is automatically enabled when selected as the system clock and disabled when not in use. See Section “4. Electrical Characteristics” on page 48 for complete oscillator specifications.

19.3. External Oscillator Drive Circuit

All C8051F99x-C8051F98x devices include an external oscillator circuit that may drive an external crystal, ceramic resonator, capacitor, or RC network. A CMOS clock may also provide a clock input. Figure 19.1 shows a block diagram of the four external oscillator options. The external oscillator is enabled and configured using the OSCXCN register.

The external oscillator output may be selected as the system clock or used to clock some of the digital peripherals (e.g., Timers, PCA, etc.). See the data sheet chapters for each digital peripheral for details. See Section “4. Electrical Characteristics” on page 48 for complete oscillator specifications.

19.3.1. External Crystal Mode

If a crystal or ceramic resonator is used as the external oscillator, the crystal/resonator and a 10 MΩ resistor must be wired across the XTAL1 and XTAL2 pins as shown in Figure 19.1, Option 1. Appropriate loading capacitors should be added to XTAL1 and XTAL2, and both pins should be configured for analog I/O with the digital output drivers disabled.

Figure 19.2 shows the external oscillator circuit for a 20 MHz quartz crystal with a manufacturer recommended load capacitance of 12.5 pF. Loading capacitors are "in series" as seen by the crystal and "in parallel" with the stray capacitance of the XTAL1 and XTAL2 pins. The total value of the each loading capacitor and the stray capacitance of each XTAL pin should equal 12.5 pF x 2 = 25 pF. With a stray capacitance of 10 pF per pin, the 15 pF capacitors yield an equivalent series capacitance of 12.5 pF across the crystal.

Note: The recommended load capacitance depends upon the crystal and the manufacturer. Please refer to the crystal data sheet when completing these calculations.

20.2.2. Using the SmaRTClock Oscillator in Self-Oscillate Mode

When using Self-Oscillate Mode, the XTAL3 and XTAL4 pins are internally shorted together. The following steps show how to configure SmaRTClock for use in Self-Oscillate Mode:

1. Set SmaRTClock to Self-Oscillate Mode (XMODE = 0).
2. Set the desired oscillation frequency:
   For oscillation at about 20 kHz, set BIASX2 = 0.
   For oscillation at about 40 kHz, set BIASX2 = 1.
3. The oscillator starts oscillating instantaneously.
4. Fine tune the oscillation frequency by adjusting the load capacitance (RTC0XCF).

20.2.3. Using the Low Frequency Oscillator (LFO)

The low frequency oscillator provides an ultra low power, on-chip clock source to the SmaRTClock. The typical frequency of oscillation is 16.4 kHz ±20%. No external components are required to use the LFO and the XTAL3 and XTAL4 pins do not need to be shorted together.

The following steps show how to configure SmaRTClock for use with the LFO:

1. Enable and select the Low Frequency Oscillator (LFOEN = 1).
2. The LFO starts oscillating instantaneously.

When the LFO is enabled, the SmaRTClock oscillator increments bit 1 of the 32-bit timer (instead of bit 0). This effectively multiplies the LFO frequency by 2, making the RTC timebase behave as if a 32.768 kHz crystal is connected at the output.

22.1. Supporting Documents

It is assumed the reader is familiar with or has access to the following supporting documents:

- The I^2C-Bus and How to Use It (including specifications), Philips Semiconductor.
- The I^2C-Bus Specification—Version 2.0, Philips Semiconductor.
- System Management Bus Specification—Version 1.1, SBS Implementers Forum.

22.2. SMBus Configuration

Figure 22.2 shows a typical SMBus configuration. The SMBus specification allows any recessive voltage between 3.0 V and 5.0 V; different devices on the bus may operate at different voltage levels.

Note: The port pins on C8051F99x-C8051F98x devices are not 5 V tolerant, therefore, the device may only be used in SMBus networks where the supply voltage does not exceed V_{DD}.

The bi-directional SCL (serial clock) and SDA (serial data) lines must be connected to a positive power supply voltage through a pullup resistor or similar circuit. Every device connected to the bus must have an open-drain or open-collector output for both the SCL and SDA lines, so that both are pulled high (recessive state) when the bus is free. The maximum number of devices on the bus is limited only by the requirement that the rise and fall times on the bus not exceed 300 ns and 1000 ns, respectively.

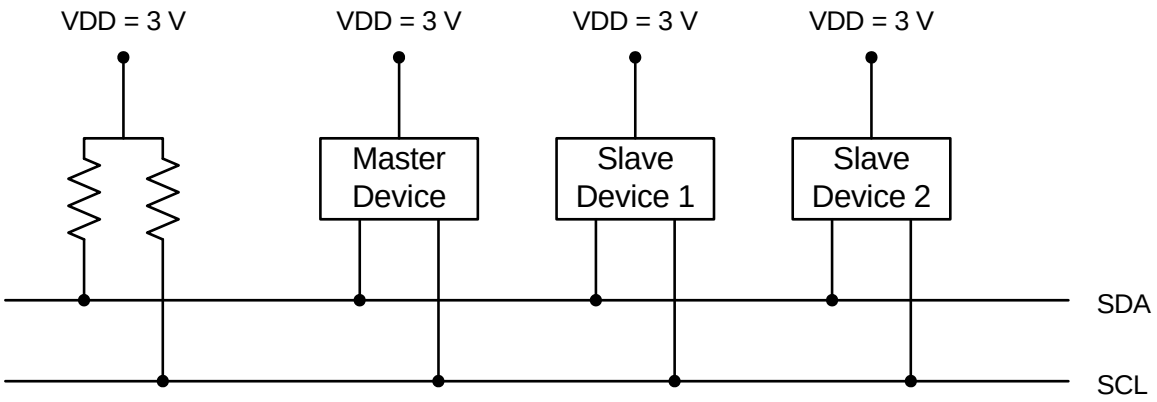

Figure 22.2. Typical SMBus Configuration

22.4.3. Hardware Slave Address Recognition

The SMBus hardware has the capability to automatically recognize incoming slave addresses and send an ACK without software intervention. Automatic slave address recognition is enabled by setting the EHACK bit in register SMB0ADM to 1. This will enable both automatic slave address recognition and automatic hardware ACK generation for received bytes (as a master or slave). More detail on automatic hardware ACK generation can be found in Section 22.4.2.2.

The registers used to define which address(es) are recognized by the hardware are the SMBus Slave Address register (SFR Definition 22.3) and the SMBus Slave Address Mask register (SFR Definition 22.4). A single address or range of addresses (including the General Call Address 0x00) can be specified using these two registers. The most-significant seven bits of the two registers are used to define which addresses will be ACKed. A 1 in bit positions of the slave address mask SLVM[6:0] enable a comparison between the received slave address and the hardware's slave address SLV[6:0] for those bits. A 0 in a bit of the slave address mask means that bit will be treated as a "don't care" for comparison purposes. In this case, either a 1 or a 0 value are acceptable on the incoming slave address. Additionally, if the GC bit in register SMB0ADR is set to 1, hardware will recognize the General Call Address (0x00). Table 22.4 shows some example parameter settings and the slave addresses that will be recognized by hardware under those conditions.

Table 22.4. Hardware Address Recognition Examples (EHACK = 1)

Hardware Slave Address SLV[6:0]	Slave Address Mask SLVM[6:0]	GC bit	Slave Addresses Recognized by Hardware
0x34	0x7F	0	0x34
0x34	0x7F	1	0x34, 0x00 (General Call)
0x34	0x7E	0	0x34, 0x35
0x34	0x7E	1	0x34, 0x35, 0x00 (General Call)
0x70	0x73	0	0x70, 0x74, 0x78, 0x7C

SFR Definition 24.2. SPI0CN: SPI0 Control

Bit	7	6	5	4	3	2	1	0
Name	SPIF	WCOL	MODF	RXOVRN	NSSMD[1:0]		TXBMT	SPIEN
Type	R/W	R/W	R/W	R/W	R/W		R	R/W
Reset	0	0	0	0	0	1	1	0

SFR Page = 0x0; SFR Address = 0xF8; Bit-Addressable

Bit	Name	Function
7	SPIF	**SPI0 Interrupt Flag.** This bit is set to logic 1 by hardware at the end of a data transfer. If SPI interrupts are enabled, an interrupt will be generated. This bit is not automatically cleared by hardware, and must be cleared by software.
6	WCOL	**Write Collision Flag.** This bit is set to logic 1 if a write to SPI0DAT is attempted when TXBMT is 0. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written. If SPI interrupts are enabled, an interrupt will be generated. This bit is not automatically cleared by hardware, and must be cleared by software.
5	MODF	**Mode Fault Flag.** This bit is set to logic 1 by hardware when a master mode collision is detected (NSS is low, MSTEN = 1, and NSSMD[1:0] = 01). If SPI interrupts are enabled, an interrupt will be generated. This bit is not automatically cleared by hardware, and must be cleared by software.
4	RXOVRN	**Receive Overrun Flag (valid in slave mode only).** This bit is set to logic 1 by hardware when the receive buffer still holds unread data from a previous transfer and the last bit of the current transfer is shifted into the SPI0 shift register. If SPI interrupts are enabled, an interrupt will be generated. This bit is not automatically cleared by hardware, and must be cleared by software.
3:2	NSSMD[1:0]	**Slave Select Mode.** Selects between the following NSS operation modes: (See Section 24.2 and Section 24.3). 00: 3-Wire Slave or 3-Wire Master Mode. NSS signal is not routed to a port pin. 01: 4-Wire Slave or Multi-Master Mode (Default). NSS is an input to the device. 1x: 4-Wire Single-Master Mode. NSS signal is mapped as an output from the device and will assume the value of NSSMD0.
1	TXBMT	**Transmit Buffer Empty.** This bit will be set to logic 0 when new data has been written to the transmit buffer. When data in the transmit buffer is transferred to the SPI shift register, this bit will be set to logic 1, indicating that it is safe to write a new byte to the transmit buffer.
0	SPIEN	**SPI0 Enable.** 0: SPI disabled. 1: SPI enabled.

26.3.6. 16-Bit Pulse Width Modulator Mode

A PCA module may also be operated in 16-Bit PWM mode. 16-bit PWM mode is independent of the other (8/9/10/11-bit) PWM modes. In this mode, the 16-bit capture/compare module defines the number of PCA clocks for the low time of the PWM signal. When the PCA counter matches the module contents, the output on CEXn is asserted high; when the 16-bit counter overflows, CEXn is asserted low. To output a varying duty cycle, new value writes should be synchronized with PCA CCFn match interrupts. 16-Bit PWM Mode is enabled by setting the ECOMn, PWMn, and PWM16n bits in the PCA0CPMn register. For a varying duty cycle, match interrupts should be enabled (ECCFn = 1 AND MATn = 1) to help synchronize the capture/compare register writes. If the MATn bit is set to 1, the CCFn flag for the module will be set each time a 16-bit comparator match (rising edge) occurs. The CF flag in PCA0CN can be used to detect the overflow (falling edge). The duty cycle for 16-Bit PWM Mode is given by Equation 26.4.

Important Note About Capture/Compare Registers: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to 0; writing to PCA0CPHn sets ECOMn to 1.

$$\text{Duty Cycle} = \frac{(65536 - PCA0CPn)}{65536}$$

Equation 26.4. 16-Bit PWM Duty Cycle

Using Equation 26.4, the largest duty cycle is 100% (PCA0CPn = 0), and the smallest duty cycle is 0.0015% (PCA0CPn = 0xFFFF). A 0% duty cycle may be generated by clearing the ECOMn bit to 0.

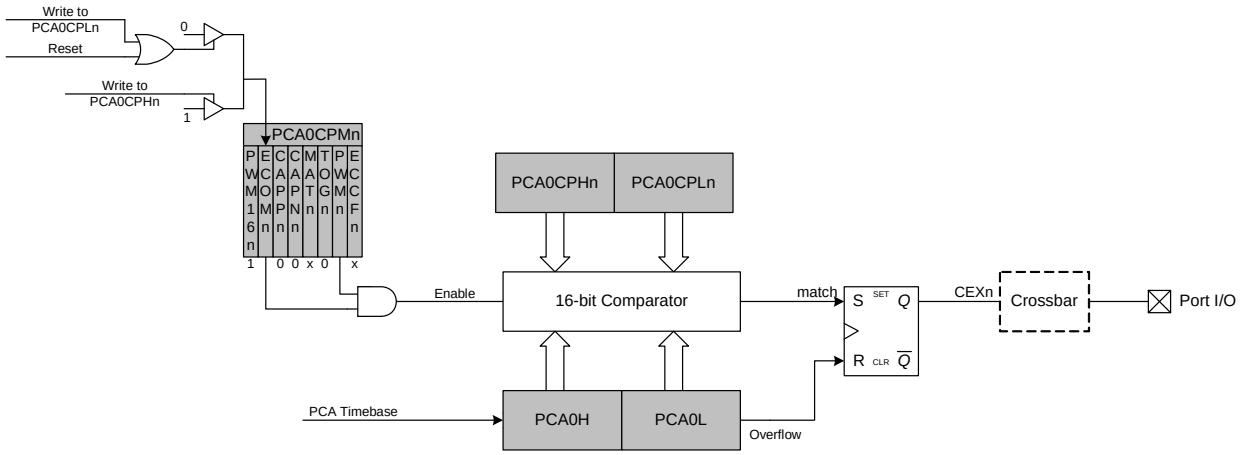

Figure 26.10. PCA 16-Bit PWM Mode

26.5. Register Descriptions for PCA0

Following are detailed descriptions of the special function registers related to the operation of the PCA.

SFR Definition 26.1. PCA0CN: PCA Control

Bit	7	6	5	4	3	2	1	0
Name	CF	CR				CCF2	CCF1	CCF0
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xD8; Bit-Addressable

Bit	Name	Function
7	CF	**PCA Counter/Timer Overflow Flag.** Set by hardware when the PCA Counter/Timer overflows from 0xFFFF to 0x0000. When the Counter/Timer Overflow (CF) interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
6	CR	**PCA Counter/Timer Run Control.** This bit enables/disables the PCA Counter/Timer. 0: PCA Counter/Timer disabled. 1: PCA Counter/Timer enabled.
5:3	Unused	Read = 000b, Write = don't care.
2:0	CCF[2:0]	**PCA Module n Capture/Compare Flag.** These bits are set by hardware when a match or capture occurs in the associated PCA Module n. When the CCFn interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.